



CC430F613x, CC430F612x, CC430F513x Device Erratasheet

1 Current Version

See [Appendix A](#) for prior silicon revisions.

✓ The checkmark means that the issue is present in the specified revision

Devices	Rev:	ADC24	ADC25	ADC27	ADC29	COMP4	CPU18	CPU20	CPU24	CPU25	CPU26	CPU27	CPU28	CPU29	CPU30	CPU31	CPU32	CPU33	CPU34	CPU35	CPU39	CPU40	DMA4
CC430F5133	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6125	E					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	E					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	E					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Devices	Rev:	DMA7	DMA8	EEM8	EEM9	EEM11	EEM13	EEM14	EEM16	EEM17	FLASH29	FLASH31	FLASH37	JTAG20	JTAG21	LCDB1	LCDB3	LCDB4	MPY1	PMAP1	PMM8	PMM9	PMM10
CC430F5133	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F5135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F5137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F6125	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Devices	Rev:	PMM11	PMM12	PMM14	PMM15	PORT15	RF1A1	RF1A2	RF1A3	RF1A5	RF1A6	RF1A8	RTC4	SYS16	TAB23	UCS6	UCS7	UCS9	UCS10	USCI26	USCI30	WDG4
CC430F5133	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6125	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

2 Package Markings

RGC64

QFN (RGC), 64 pin

○	CC430Fxxxx	TI	= TI
		YM	= Year and Month Date Code
		LLLL	= LOT Trace Code
	TI YMS #	S	= Assembly Site Code
	LLLL <u>G4</u>	#	= DIE Revision
		o	= PIN 1

RGZ48

QFN (RGZ), 48 Pin

○	CC430	TI	= TI
	Fxxxx	YM	= Year and Month Date Code
		LLLL	= LOT Trace Code
	TI YMS #	S	= Assembly Site Code
	LLLL <u>G4</u>	#	= DIE Revision
		o	= PIN 1

3 Detailed Bug Description

ADC24

ADC12 Module

Function

Unexpected ADC12 current draw when ADC12ENC = 1

Description

When set, the ADC12ENC bit issues a clock request to the selected source clock, even before the conversion trigger. This causes some extra current consumption, depending on the selected clock.

Workaround

None

ADC25

ADC12 Module

Function

Write to ADC12CTL0 triggers ADC12 when CONSEQ = 00

Description

If ADC conversions are triggered by the Timer_B module and the ADC12 is in single-channel single-conversion mode (CONSEQ = 00), ADC sampling is enabled by write access to any bit(s) in the ADC12CTL0 register. This is contrary to the expected behavior that only the ADC12 enable conversion bit (ADC12ENC) triggers a new ADC12 sample.

Workaround

When operating the ADC12 in CONSEQ = 00 and a Timer_B output is selected as the sample and hold source, temporarily clear the ADC12ENC bit before writing to other bits in the ADC12CTL0 register. The following capture trigger can then be re-enabled by setting ADC12ENC = 1.

ADC27	ADC12 Module
Function	Integral and differential non-linearity exceed specifications
Description	<p>The ADC12_A integral and differential non-linearity may exceed the limits specified in the data sheet under the following conditions:</p> <ul style="list-style-type: none"> • If the internal voltage reference generator is used and • If the reference voltage is not buffered off-chip and • If $f_{\text{ADC12CLK}} > 2.7 \text{ MHz}$ or If the internal voltage reference is selected for 1.5-V output mode. <p>The non-linearity can be up to tens of LSBs. This is due to the internal reference buffer providing insufficient drive for the switched capacitor array of the ADC12_A.</p>
Workaround	<ul style="list-style-type: none"> • Turn on the output of the internal voltage reference to increase the drive strength of the reference to the ADC_12 core: <ul style="list-style-type: none"> – If REFMSTR bit in REFCTL0 is 0 (allowing Shared REF to be controlled by ADC_A reference control bits) <ul style="list-style-type: none"> Set ADC12REFON bit in ADC12CTL0 = 1 and Set ADC12REFOUT bit in ADC12CTL2 = 1 – If REFMSTR bit in REFCTL0 is 1 <ul style="list-style-type: none"> Set REFON and REFOUT bits in REFCTL0 = 1 or • Ensure $f_{\text{ADC12CLK}} < 2.7 \text{ MHz}$ and select the internal voltage reference in 2.5-V output mode. Depending on the frequency of the source of f_{ADC12CLK} (ACLK, MCLK, SMCLK, or MODOSC), select the divider bits accordingly. <ul style="list-style-type: none"> – If $f_{\text{ADC12CLK}} = \text{MODOSC (ADC12OSC)}$ <pre>ADC12CTL1 = ADC12DIV_2; // Divide clock by 2</pre> – If $f_{\text{ADC12CLK}} = \text{ACLK/SMCLK/MCLK} > 2.7 \text{ MHz}$ Use ADC12DIVx and/or ADC12PDIVx bits to reduce the selected clock frequency to between 0.45 MHz and 2.7 MHz. And set both REFVSELx bits in REFCTL0 to REFVSEL_3 (select 2.5-V output).
ADC29	ADC12 Module
Function	Incorrect temperature sensor calibration data
Description	<p>In some devices, the internal temperature sensor calibration data for 30°C are invalid for all V_{Ref} conditions. Devices with correct calibration data show a difference of at least 30 LSBs between the different V_{Ref} conditions. When using incorrect calibration data with the internal temperature sensor ADC samples, the calculated results can be unreliable. Calibration data for 85°C are not affected.</p>
Workaround	Recalibrate the temperature sensor for 30°C at the application level.

COMP4	<i>Comparator_B Module</i>
Function	CBEX and CBOUTPOL bits do not invert comparator I/O
Description	Setting the exchange bit, CBEX, does not interchange the comparator inputs. Similarly setting the output polarity bit, CBOUTPOL, does not invert the output of the comparator.
Workaround	To obtain an inverted output from the comparator, invert the input signals to the comparator using the channel input selector bits, CBIPSEL_x and CBIMSEL_x. Make sure to use a MOV instruction so that the inputs are inverted simultaneously.
CPU18	<i>CPU Module</i>
Function	LPM instruction can corrupt PC/SR registers
Description	<p>The PC and SR registers have the potential to be corrupted when:</p> <ul style="list-style-type: none"> An instruction using register, absolute, indexed, indirect, indirect auto-increment, or symbolic mode is used to set the LPM bits (e.g., <code>BIS &xyh, SR</code>). and This instruction is followed by a CALL or CALLA instruction. <p>Upon servicing an interrupt service routine, the program counter (PC) is pushed twice onto the stack instead of the correct operation where the PC, then the SR registers are pushed onto the stack. This corrupts the SR and possibly the PC on RETI from the ISR.</p>
Workaround	Insert a NOP or <code>__no_operation()</code> intrinsic function between the instruction to enter low-power mode and the CALL or CALLA instruction.
CPU20	<i>CPU Module</i>
Function	An unexpected Vacant Memory Access Flag (VMAIFG) can be triggered due to the CPU autoincrement of the MAB+2 outside the range of a valid memory block.
Description	<p>The VMAIFG can be triggered under the following conditions:</p> <ol style="list-style-type: none"> If an interrupt is requested, fetched by the CPU, but lost before execution of the interrupt service routine. or If a PC-modifying instruction (for example, RET, PUSH, CALL, POP, JMP, BR) is fetched from the last address of a section of memory (Flash or RAM) that is not contiguous to a higher valid section on the memory map.
Workaround	<p>For case 1 – None</p> <p>For case 2 – If code is affected, edit the linker command file to make the last four bytes of affected memory sections unavailable.</p>

CPU24	CPU Module
Function	Program counter corruption following entry into low-power mode
Description	<p>The program counter is corrupted when an interrupt event occurs in the time between (and including) one cycle before and one cycle after the CPUOFF bit is set in the status register. This failure occurs when the BIS instruction is followed by a CALL or CALLA instruction using the following addressing modes:</p> <p>BIS &, SR CALLA indir, indir autoinc, reg BIS INDEX, SR CALLA indir, indir autoinc, reg BIS reg, SR CALLA reg, indir, indir autoinc</p> <hr/> <p>NOTE: Due to the instruction emulation, the EINT instruction, as well as the <code>__enable_interrupts()</code> and possibly the <code>__bis_SR_register()</code> intrinsic functions are affected.</p> <hr/>
Workaround	Insert a NOP instruction or <code>__no_operation()</code> intrinsic function call between the BIS and CALL or CALLA instructions.
CPU25	CPU Module
Function	DMA transfer does not execute during low-power mode
Description	<p>If the following instruction sequence is used ([] denotes an addressing mode) to enter a low-power mode, and the DMARMWDIS bit is set, then DMA transfers are blocked for the duration of the low-power mode.</p> <p>BIS [register index absolute symbolic],SR CALLA [register]</p>
Workaround	<ul style="list-style-type: none"> Insert a NOP instruction or <code>__no_operation()</code> intrinsic function call between the BIS and CALLA instructions or Temporarily disable the DMARMWDIS bit when entering low-power mode.
CPU26	CPU Module
Function	CALL SP does not behave as expected
Description	When the intention is to execute code from the stack, a CALL SP instruction skips the first piece of data (instruction) on the stack. The second piece of data at SP + 2 is used as the first executable instruction.
Workaround	Write the op code for a NOP as the first instruction on the stack. Begin the intended subroutine at address SP + 2.

CPU27
CPU Module
Function

Program Counter (PC) is corrupted during the context save of a nested interrupt

Description

When a low-power mode is entered within an interrupt service routine that has enabled nested interrupts (by setting the GIE bit), and the instruction that sets the low-power mode is directly followed by a RETI instruction, an incorrect value of PC + 2 is pushed to the stack during the context save. Hence, the RETI instruction is not executed on return from the nested interrupt, and the PC becomes corrupted.

Workaround

Insert a NOP or `__no_operation()` intrinsic function between the instruction that sets the lower power mode and the RETI instruction.

CPU28
CPU Module
Function

PC is corrupted when using certain extended addressing mode combinations

Description

An extended memory instruction that modifies the program counter executes incorrectly when preceded by an extended memory write-back instruction under the following conditions:

First instruction:

2-operand instruction, extended mode using (register,index), (register,absolute), or (register,symbolic) addressing modes

Second instruction:

2-operand instruction, extended mode using the (indirect,PC), (indirect auto-increment,PC), or (indexed [with ind 0], PC) addressing modes

Example

```
BISX.A  R6, &AABCD
ANDX.A  @R4+, PC
```

Workaround

- Insert a NOP or a `__no_operation()` intrinsic function between the two instructions.
- or
- Do not use an extended memory instruction to modify the PC.

CPU29***CPU Module*****Function**

Using a certain instruction sequence to enter low-power mode(s) affects the instruction width of the first instruction in an NMI ISR

Description

If there is a pending NMI request when the CPU enters a low-power mode (LPMx) using an instruction of Indexed source addressing mode, and that instruction is followed by a 20-bit wide instruction of Register source and Destination addressing modes, the first instruction of the ISR is executed as a 20-bit wide instruction.

Example

```
main:
    ...
    MOV.W   [indexed],SR           ; Enter LPMx
    MOVX.A  [register],[register]  ; 20-bit wide instruction
    ...
ISR_start:
    MOV.B   [indexed],[register]   ; ERROR - Executed as a 20-bit
instruction!
```

Note: [] indicates addressing mode

Workaround

- Insert a NOP or a `__no_operation()` intrinsic function following the instruction that enters the LPMx using indexed addressing mode.
- or
- Use a NOP or a `__no_operation()` intrinsic function as first instruction in the ISR.
- or
- Do not use the indexed mode to enter LPMx.

CPU30***CPUX Module*****Function**

ADDA, SUBA, CMPA [immediate],PC behave as if immediate value were offset by -2

Description

The extended address instructions ADDA, SUBA, and CMPA in immediate addressing mode are represented by 4 bytes of opcode (see the *MSP430F5xx Family User's Guide (SLAU208)* for more details). In cases where the program counter (PC) is used as the destination register, only 2 bytes of the current instruction's 4-byte opcode are accounted for in the PC value. The resulting operation executes as if the immediate value were offset by a value of -2.

Example

Ideal: ADDA #Immediate-4, PC ...is equivalent to...

Actual: ADDA #Immediate-2, PC

NOTE: The MOV instruction is not affected.

Workaround

- Modify immediate value in software to account for the offset of 2.
- or
- Use extended 20-bit instructions (addx.a, subx.a, cmpx.a) instead.

CPU31	CPUX Module
Function	SP corruption
Description	When the instruction PUSHX.A is executed using the indirect auto-increment mode with the stack pointer (SP) as the source register [PUSHX.A @SP+], the SP is consequently corrupted. Instead of decrementing the value of the SP by four, the value of the SP is replaced with the data pointed to by the SP previous to the PUSHX.A instruction execution.
Workaround	None. The compiler does not generate a PUSHX.A instruction that involves the SP.
CPU32	CPUX Module
Function	CALLA PC executes incorrectly
Description	When the instruction CALLA PC is executed, the program counter (PC) that is pushed onto the stack during the context save is incorrectly offset by a value of -2.
Workaround	None. The compiler does not generate a CALLA PC instruction.
CPU33	CPUX Module
Function	CALLA [indexed] may corrupt the program counter
Description	When the Stack Pointer (SP) is used as the destination register in the CALLA index(Rdst) instruction and is preceded by a PUSH or PUSHX instruction in any of the following addressing modes: Absolute, Symbolic, Indexed, Indirect register, or Indirect auto-increment, the "index" of the CALLA instruction is not sign extended to 20-bits and is always treated as a positive value. This causes the Program Counter to be set to a wrong address location when the index of the CALLA instruction represents a negative offset.
	<p>NOTE: This erratum applies only when the instruction sequence is: PUSH or PUSHX followed by CALLA index(SP).</p> <p>This erratum does not apply if the PUSH or PUSHX instruction is used in the Register or Immediate addressing mode.</p> <p>This erratum applies only when SP is used as the destination register in the CALLA index(Rdst) instruction.</p>
Workaround	Place a NOP instruction in between the PUSH or PUSHX and the CALLA index(SP) instructions.
	<p>NOTE: This bug has no compiler impact as the compiler does not generate a CALLA instruction that uses indexed addressing mode with the SP.</p>

CPU34***CPU Module*****Function**

CPU may be halted if a conditional jump is followed by a rotate PC instruction

Description

If a conditional jump instruction (JZ, JNZ, JC, JNC, JN, JGE, JL) is followed by an Address Rotate instruction on the PC (RRCM, RRAM, RLAM, RRUM) and the jump is not performed, the CPU is halted.

Workaround

Insert a NOP between the conditional jump and the rotate PC instructions.

CPU35***CPU Module*****Function**

Instruction `BIT.B @Rx, PC` uses the wrong PC value

Description

The BIT(.B/.W) instruction in indirect register addressing mode is represented by 2 bytes of opcode. And if Program Counter (PC) is used as the destination register, the 2 opcode bytes of the current BIT instruction are not accounted for. The resulting operation executes the instruction using the wrong PC value, and this affects the results in the Status Register (SR).

Workaround

None

NOTE: The compiler does not generate a BIT instruction that uses the PC as an operand.

CPU39***CPU Module*****Function**

PC is corrupted when single-stepping through an instruction that clears the GIE bit

Description

Single-stepping over an instruction that clears the General Interrupt Enable bit (for example, `DINT` or `BIC #GIE, SR`) when the GIE bit was previously set may corrupt the PC. For example, `DINT` or `BIC #GIE, SR` is a 2-byte instruction. Single stepping through this instruction increments the PC by a value of 4 instead of 2, thus corrupting the next PC value.

NOTE: This erratum applies to debug mode only.

Workaround

Insert a NOP or `__no_operation()` intrinsic immediately after the line of code that clears the GIE bit.

CPU40

CPU Module

Function

PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section

Description

If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.

For example, a conditional jump instruction followed by data section (0140h).

```
@0x8012 Loop    DEC.W R6
@0x8014         DEC.W R7
@0x8016         JNZ Loop
@0x8018 Value1  DW 0140h
```

Workaround

In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.

DMA4

DMA Module

Function

Corrupted write access to 20-bit DMA registers

Description

When a 20-bit wide write to a DMA address register (DMAxSA or DMAxDA) is interrupted by a DMA transfer, the register contents may be unpredictable.

Workaround

- Design the application to ensure that no DMA access interrupts 20-bit wide accesses to the DMA address registers.
or
- When accessing the DMA address registers, enable the Read Modify Write disable bit (DMARMWDIS = 1), or temporarily disable all active DMA channels (DMAEN = 0).
or
- Use word access for accessing the DMA address registers. Note that this limits the values that can be written to the address registers to 16-bit values (lower 64K of flash).

DMA7

DMA Module

Function

DMA interrupt lost

Description

If a DMA request is received during the time when the read address of a read modify write instruction is on the Memory Address Bus (MAB), application interrupts could be lost.

Workaround

Set the DMARMWDIS bit when using the DMA.

DMA8***DMA Module*****Function**

DMA can corrupt values on write-access to program stack

Description

If the DMA controller makes a write access to the stack while executing one of the following instructions, the data that is written may be corrupted.

CALLA [REG | IDX | SYM | ABS | IND | INA | IMM]

PUSHX.A [IDX | SYM | ABS | IND | IMM | INA]

PUSHX.A [REG]

PUSHM.A [REG]

POPM.A [REG]

Note: [] denotes an addressing mode

Workaround

Do not declare function-scope variables. Declare all variables that are intended to be modified by the DMA as global- or file-scope such that they are allocated in the data section of RAM and not on the program stack.

EEM8***Enhanced Emulation Module*****Function**

Debugger stops responding when using the DMA

Description

In repeated transfer mode, the DMA automatically reloads the size counter (DMAxSZ) once a transfer is complete and immediately continues to execute the next transfer unless the DMA Enable bit (DMAEN) has been previously cleared. In burst-block transfer mode, DMA block transfers are interleaved with CPU activity 80/20% – of ten CPU cycles, eight are allocated to a block transfer and two are allocated for the CPU.

Because the JTAG system must wait for the CPU bus to be clear to halt the device, it can only do so when two conditions are met:

- Three clock cycles after any DMA transfer, the DMA is no longer requesting the bus.
and
- The CPU is not requesting the bus.

Therefore, if the DMA is configured to operate in the repeat burst-block transfer mode, and a breakpoint is set between the line of code that triggers the DMA transfers and the line that clears the DMAEN bit, the DMA always requests the bus and the JTAG system never gains control of the device.

Workaround

When operating the DMA in repeat burst-block transfer mode, set breakpoint(s) only when the DMA transfers are not active (before the start or after the end of the DMA transfers).

EEM9***Enhanced Emulation Module*****Function**

Combined triggers on the PUSH instruction may be missed

Description

When the PUSH instruction is used in any addressing mode except register or immediate modes, a combined trigger may be missed when its conditions are defined by a PUSH instruction fetch and a successful match of the value being pushed onto stack.

Workaround

None

EEM11	<i>Enhanced Emulation Module</i>
Function	Condition register write trigger fails while executing rotate instructions
Description	When using breakpoints or single stepping in the presence of multiple background-interrupts, the debugger may not halt at the breakpoint location and instead halts at the first line of any interrupt service routine.
Workaround	None
	<hr/> NOTE: This erratum applies to debug mode only. <hr/>
EEM13	<i>Enhanced Emulation Module</i>
Function	Halting the debugger does not return correct PC value when in LPM
Description	When debugging, if the device is in any low-power mode and the debugger is halted, the program counter update by the debugger is corrupted. The debugger is unable to halt at the correct location.
Workaround	None
	<hr/> NOTE: This erratum applies to debug mode only. <hr/>
EEM14	<i>Enhanced Emulation Module</i>
Function	Single-step or breakpoint on module register with WAIT capability may not work
Description	In debug mode, the CPU clock is driven independently from the wait inputs of device modules (i.e., MULT, USB, RF1A, CRC). As a result, an EEM halt on an access to the module data registers (breakpoint or single-step) may show incorrect results due to incomplete execution.
Workaround	Do not single-step through a data register access that holds the CPU to provide a valid result. Place breakpoints after the affected register is accessed and sufficient clock cycles have been provided.
	<hr/> NOTE: This erratum applies to debug mode only. <hr/>

EEM16	<i>Enhanced Emulation Module</i>
Function	The state storage display does not work reliably when used on instructions with CPU Wait cycles.
Description	When executing instructions that require wait states; the state storage window updates incorrectly. For example a flash erase instruction causes the CPU to be held until the erase is completed i.e. the flash puts the CPU in a wait state. During this time if the state storage window is enabled it may incorrectly display any previously executed instruction multiple times.
	<hr/> NOTE: This erratum affects debug mode only. <hr/>
Workaround	Do not enable the state storage display when executing instructions that require wait states. Instead set a breakpoint after the instruction is completed to view the state storage display.
EEM17	<i>Enhanced Emulation Module</i>
Function	Wrong Breakpoint halt after executing Flash Erase/Write instructions
Description	Hardware breakpoints or Conditional Address triggered breakpoints on instructions that follow Flash Erase/Write instructions, stops the debugger at the actual Flash Erase/Write instruction even though the flash erase/write operation has already been executed. The hardware/conditional address triggered breakpoints that are placed on either the next two single opcode instructions OR the next double opcode instruction that follows the Flash Erase/Write instruction are affected by this erratum.
	<hr/> NOTE: This erratum affects debug mode only. <hr/>
Workaround	None. Use other conditional/advanced triggered breakpoints to halt the debugger right after Flash erase/write instructions.
FLASH29	<i>Flash Module</i>
Function	Read disturb due to emergency exit from write/erase Flash operation
Description	When a Flash write or erase is abruptly terminated, any further reliable reads from Flash are not ensured. The abrupt termination can occur as a result of the Emergency Exit bit (EMEX in FCTL3) being set. This forces a write or an erase operation to be terminated before normal completion.
Workaround	After setting EMEX = 1, wait for at least 100 μ s after a bank or mass erase and at least 6 μ s after a segment erase before Flash is accessed again.
FLASH31	<i>Flash Module</i>
Function	Interrupts not disabled during flash operation
Description	When a flash operation is in progress, interrupts are not automatically disabled. The CPU will always attempt to service the interrupt request, whether or not the flash is busy.
Workaround	Disable interrupts using the GIE bit before erasing flash in another bank of memory. Note that all interrupts during this period of time remain pending until GIE = 1.

FLASH37

Flash Module

Function

Corrupted flash read when SVM low-side flag is triggered

Description

If the SVM low side is enabled, a change in the VCORE voltage level (an increase in the VCORE level) may cause the currently executed read operation from flash to be incorrect and may lead to unexpected code execution or incorrect data. This can happen under any one of the following conditions:

- When the VCORE is changed in the application, the SVM low side is used to indicate if the core voltage has settled by using the SVM DLYIFG flag. The failure occurs only when a flash access is concurrent with the expiration of the settling time delay.
- Unexpected changes in the VCORE voltage level

For code examples and detailed guidance on the PMM operation, see the application report *MSP430F5xx and MSP430F6xx Core Libraries* ([SLAA448](#)).

Workaround

- Execute the procedure to change the VCORE level from RAM.
or
- If executing from flash, follow the procedure below when increasing the VCORE level. Note: To apply this workaround, the SVM low-side comparator must operate in normal mode (SVMLFP = 0 in SVMLCTL).

```
// Set SVM highside to new level and check if a VCore increase is possible
SVSMHCTL = SVMHE | SVSHE | (SVSMHRRLO * level);
// Wait until SVM highside is settled
while ((PMMIFG & SVSMHDLYIFG) == 0);
// Clear flag
PMMIFG &= ~SVSMHDLYIFG;

// Set also SVS highside to new level
// Vcc is high enough for a Vcore increase
SVSMHCTL |= (SVSHRVL0 * level);
// Wait until SVM highside is settled
while ((PMMIFG & SVSMHDLYIFG) == 0);
// Clear flag
PMMIFG &= ~SVSMHDLYIFG;

//*****flow change for errata workaround *****
// Set VCore to new level
PMMCTL0_L = PMMCOREV0 * level;

// Set SVM, SVS low side to new level
SVSMLCTL = SVMLE | (SVSMLRRL0 * level) | SVSLE | (SVSLRVL0 * level);
// Wait until SVM, SVS low side is settled
while ((PMMIFG & SVSMLDLYIFG) == 0);
// Clear flag
PMMIFG &= ~SVSMLDLYIFG;

//*****flow change for errata workaround *****
```

JTAG20**JTAG Module****Function**

BSL does not exit to application code

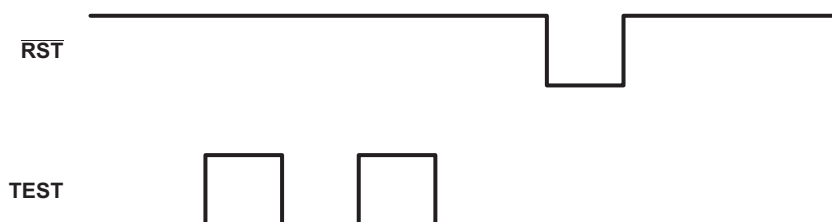
Description

The methods used to exit the BSL per *MSP430 Programming Via the Bootstrap Loader (SLAU319)* are invalid.

Workaround

To exit the BSL one of the following methods must be used.

- A power cycle
or
- Toggle the TEST pin twice when $\overline{\text{RST}}$ is high, and then pull $\overline{\text{RST}}$ low.



NOTE: This sequence is not subject to timing constraints and the appropriate level transitions are sufficient to trigger an exit from BSL mode.

JTAG21**JTAG Module****Function**

"Attach to Running Target" resets device

Description

The "attach to running target" feature in IAR occasionally resets the device before getting it under JTAG control.

Workaround

Use alternative methods (for example, outputting device status/variables via port pins or UART) to debug unattached running target.

LCDB1**LCD_B Module****Function**

VLCDEXT bit not working properly

Description

When the VLCDEXT bit is set an external voltage applied to the LCDCAP/R33 pin should serve as the LCD voltage. This works as expected when the V2 to V4 voltages are generated externally (LCDEXTBIAS = 1) and external resistors are connected on the R03 to R33 resistor ladder. If internal V2 to V4 bias voltage generation is selected (LCDEXTBIAS = 0), applying an external LCD voltage on LCDCAP VLCDEXT has no effect.

Workaround

The expected behavior for the VLCDEXT bit can be achieved by setting the VLCDx bits to a non-zero value and leaving the charge pump disabled (LCDPEN = 0). The VLCDx bits don't care when the charge pump is disabled so this does not result in any additional or unexpected current consumption.

LCDB3	<i>LCD_B Module</i>
Function	LCDFRMIFG set erroneously when LCDON changed from 1 to 0
Description	The LCD_B frame interrupt flag (LCDFRMIFG) can be set erroneously when the interrupt is enabled ((LCDFRMIE = 1) and the LCD_B module is switched off (LCDON changed from 1 to 0).
Workaround	Disable the frame interrupt before switching off the LCD_B module.
LCDB4	<i>LCD_B Module</i>
Function	Write access to LCDBIV does not reset LCD IFGs
Description	A write access to the LCDBIV register does not automatically reset all pending interrupt flags.
Workaround	Clear all interrupt flags in software by writing 0 to the lowest nibble of LCDBCTL1, where the flags are stored.
MPY1	<i>Hardware Multiplier (MPY) Module</i>
Function	Save and Restore feature on MPY32 not functional
Description	The MPY32 module uses the Save and Restore method which involves saving the multiplier state by pushing the MPY configuration/operand values to the stack before using the multiplier inside an Interrupt Service Routine (ISR) and then restoring the state by popping the configuration/operand values back to the MPY registers at the end of the ISR. However due to the erratum the Save and Restore operation fails causing the write operation to the OP2H register right after the restore operation to be ignored as it is not preceded by a write to OP2L register resulting in an invalid multiply operation.
Workaround	None. Disable interrupts when writing to OP2L and OP2H registers.
<p>NOTE: When using the C-compiler, the interrupts are automatically disabled while using the MPY32.</p>	
PMAP1	<i>Port Mapping Controller</i>
Function	Port Mapping Controller does not clear unselected inputs to mapped module
Description	The Port Mapping Controller provides the logical OR of all port mapped inputs to a module (Timer, USCI, etc). If the PSEL bit (PxSEL.y) of a port mapped input is cleared, then the logic level of that port mapped input is latched to the current logic level of the input. If the input is in a logical high state, then this high state is latched into the input of the logical OR. In this case, the input to the module is always a logical 1 regardless of the state of the selected input.
Workaround	<ul style="list-style-type: none"> • Drive input to the low state before clearing the PSEL bit of that input and switching to another input source. or • Use the Port Mapping Controller reconfiguration feature, PMAPRECFG, to select inputs to a module and map only one input at a time.

PMM8 *Power Management Module*

Function Supply current in LPM4.5 is unpredictable

Description Due to an unpredictable value of the supply current in LPM4.5, the mode should not be used.

Workaround None

PMM9 *Power Management Module*

Function False SVSxIFG events

Description The comparators of the SVS require a certain amount of time to stabilize and output a correct result once re-enabled; this time is different for the Full Performance versus the Normal mode. The time to stabilize the SVS comparators is intended to be accounted for by a built-in event-masking delay of 2 μ s when Full Performance mode is enabled.

However, the comparators of the SVS in Full Performance mode take longer than 2 μ s to stabilize, so the possibility exists that a false positive will be triggered on the SVSH or SVSL. This results in the SVSxIFG flags being set and, depending on the configuration of SVSxPE bit, a POR can also be triggered .

Additionally, when the SVSxIFGs are set, all GPIOs are three-state; that is, floating until the SVSx comparators are settled.

The SVS IFGs are falsely set under the following conditions:

1. Wakeup from LPM2/3/4 when SVSxMD = 0 (default setting) and SVSxFP = 1. The SVSx comparators are disabled automatically in LPM2/3/4 and are then re-enabled on return to active mode.
2. SVSx is turned on in full performance mode (SVSxFP = 1).
3. A PUC/POR occurs after SVSx is disabled. After a PUC or POR, the SVSx are enabled automatically, but the settling delay is not triggered. Based on the SVSxPE bit, this may lead to POR events until the SVS comparator is fully settled.

Workaround For each of the above listed conditions the following workarounds apply:

1. If the Full Performance mode is to be enabled for either the high-side or low-side SVS comparators, the respective SVSxMD bits must be set (SVSxMD = 1) such that the SVS comparators are not temporarily shut off in LPM2/3/4. Note that this is equivalent to a 2 μ A (typical) adder to the low-power mode current, per the device-specific data sheet, for each SVSx that remains enabled.
2. The SVSx must be turned on in normal mode (SVSxFP = 0). It can be reconfigured to use full performance mode once the SVSx/SVMx delay has expired.
3. Ensure that SVSH and SVSL are always enabled.

PMM10 *Power Management Module*

Function SVS/SVM flags disabled after Power Up Clear reset

Description SVS/SVM interrupt flags are not set after a Power Up Clear (PUC) Reset if the SVS was disabled before the PUC reset was applied.

Workaround A write access to the intended SVSx register after PUC re-enables the SVS and SVM interrupt flags.

PMM11	Power Management Module
Function	MCLK comes up fast on exit from LPM3 and LPM4
Description	The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for a period of time up to 6 μ s. This behavior is masked from affecting code execution by default: SVSL and SVML run in normal-performance mode and mask CPU execution for 150 μ s on wakeup from LPM3 and LPM4. However, when the low-side SVS and the SVM are disabled or operating in full-performance mode (that is, SVMLE = 0, SVSLE = 0, or SVMLFP = 1, SVSLFP = 1) and MCLK is sourced from the internal DCO running over 4 MHz, 7 MHz, 11 MHz, or 14 MHz at core voltage levels 0, 1, 2, or 3, respectively, the mask lasts only 2 μ s. MCLK is, therefore, susceptible to run out of spec for 4 μ s.
Workaround	Set the MCLK divide bits in the Unified Clock System Control 5 Register (UCSCTL5) to divide MCLK by two prior to entering LPM3 or LPM4 (set DIVMx = 001). This prevents MCLK from running out of spec when the CPU wakes from the low power mode. Following the wakeup from the low power mode, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before resetting DIVMx to zero and running MCLK at full speed [for example, <code>__delay_cycles(100)</code>].
PMM12	Power Management Module
Function	SMCLK comes up fast on exit from LPM3 and LPM4
Description	The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for a period of time up to 6 μ s. When SMCLK is sourced by the DCO, it is not masked on exit from LPM3 or LPM4. Therefore, SMCLK exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 μ s. The increased frequency has the potential to change the expected timing behavior of peripherals that select SMCLK as the clock source.
Workaround	<ul style="list-style-type: none"> • Use XT2 as the SMCLK oscillator source instead of the DCO. or • Do not disable the clock request bit for SMCLKREQEN in the Unified Clock System Control 8 Register (UCSCTL8). This means that all modules that depend on SMCLK to operate successfully should be halted or disabled before entering LPM3 or LPM4. If the increased frequency prevents the proper function of an affected module, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before re-enabling the module [for example, <code>__delay_cycles(100)</code>].
PMM14	Power Management Module
Function	Increasing the core level when SVS/SVM low side is configured in full-performance mode causes device reset
Description	When the SVS/SVM low side is configured in full performance mode (SVSMLCTL.SVSLFP = 1), the settling time delay for the SVS comparators is approximately 2 μ s. When increasing the core level in full-performance mode; the core voltage does not settle to the new level before the settling time delay of the SVS/SVM comparator expires. This results in a device reset.
Workaround	When increasing the core level, enable the SVSSV/M low side in normal mode (SVSMLCTL.SVSLFP = 0). This provides a settling time delay of approximately 150 μ s, allowing the core sufficient time to increase to the expected voltage before the delay expires.

PMM15 *Power Management Module (SVxH and SVxL)*

Function Device may not wake up from LPM2, LPM3, or LPM4

Description Device may not wake up from LPM2, LPM3, or LPM4 if an interrupt occurs within 1 μ s after entry to the specified LPMx; entry can be caused either by user code or automatically (for example, after a previous ISR is completed). Device can be recovered with an external reset or a power cycle. Additionally, a PUC can also be used to reset the failing condition and bring the device back to normal operation (for example, a PUC caused by the WDT).

This effect is seen when:

- A write to the SVSMHCTL and SVSMLCTL registers is immediately followed by an LPM2, LPM3, or LPM4 entry without waiting the requisite settling time (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0).
- or
- The following two conditions are met:
 - The SVS_L/SVM_L module is configured for a fast wake-up or the SVS_L/SVM_L module is turned off. The affected SVSMLCTL register settings are shown as shaded in the following table.

SVSL	SVSLE	SVSLMD	SVSLFP	AM,LPM0/1 SVSL State	Manual SVSMLACE=0	Automatic SVSMLACE=1	Wakeup Time LPM2/3/4
					LPM2/3/4 SVSL State	LPM2/3/4 SVSL State	
	0	x	x	OFF	OFF	OFF	t _{WAKE-UP FAST}
	1	0	0	Normal	OFF	OFF	t _{WAKE-UP SLOW}
	1	0	1	Full Performance	OFF	OFF	t _{WAKE-UP FAST}
	1	1	0	Normal	Normal	OFF	t _{WAKE-UP SLOW}
	1	1	1	Full Performance	Full Performance	Normal	t _{WAKE-UP FAST}
SVML	SVMLE	SVMLFP		AM,LPM0/1 SVML State	Manual SVSMLACE=0	Automatic SVSMLACE=1	Wakeup Time LPM2/3/4
					LPM2/3/4 SVML State	LPM2/3/4 SVML State	
	0	x		OFF	OFF	OFF	t _{WAKE-UP FAST}
	1	0		Normal	Normal	OFF	t _{WAKE-UP SLOW}
1	1		Full Performance	Full Performance	Normal	t _{WAKE-UP FAST}	

and

- The SVS_H/SVM_H module is configured to transition from Normal mode to an OFF state when moving from Active/LPM0/LPM1 into LPM2/3/4 modes. The affected SVSMHCTL register settings are shown as shaded in the following table.

SVSH	SVSHE	SVSHMD	SVSHFP	AM, LPM0/1 SVSH State	Manual SVSMHACE=0	Manual SVSMHACE=1
					LPM2/3/4 SVSH State	LPM2/3/4 SVSH State
	0	x	x	OFF	OFF	OFF
	1	0	0	Normal	OFF	OFF
	1	0	1	Full Performance	OFF	OFF
	1	1	0	Normal	Normal	OFF
	1	1	1	Full Performance	Full Performance	Normal
SVMH	SVSHE	SVMHFP		AM, LPM0/1 SVSH State	Manual SVSMHACE=0	Manual SVSMHACE=1
					LPM2/3/4 SVSH State	LPM2/3/4 SVSH State
	0	x		OFF	OFF	OFF
	1	0		Normal	Normal	OFF
	1	1		Full Performance	Full Performance	Normal

Workaround

- Any write to the SVSMxCTL register must be followed by a settling delay (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0) before entering LPM2, LPM3, or LPM4.
and
- Ensure the SVSx and SVMx are configured to prevent the issue from occurring by the following:
 - Configure the SVS_L module for slow wake up (SVSLFP = 0). Note that this increases the wakeup time from LPM2, LPM3, or LPM4 to $t_{\text{WAKE-UP SLOW}}$ (approximately 150 μs).
 - or
 - Do not configure the SVS_H and SVM_H such that the modules transition from Normal mode to an OFF state on LPM entry. Instead, force the modules to remain ON even in LPMx. Note that this causes increased power consumption when in LPMx.

See the *MSP430F5xx and MSP430F6xx Core Libraries* ([SLAA448](#)) for proper PMM configuration functions.

Use the following function, PMM15Check (void), to determine whether or not the existing PMM configuration is affected by the erratum. The return value of the function is 1 if the configuration is affected, and 0 if the configuration is not affected.

```
unsigned char PMM15Check (void)
{
    // First check if SVSL/SVML is configured for fast wake-up
    if ( (!(SVSMLCTL & SVSLE)) || ((SVSMLCTL & SVSLE) && (SVSMLCTL & SVSLFP)) ||
        (!(SVSMLCTL & SVMLE)) || ((SVSMLCTL & SVMLE) && (SVSMLCTL & SVMLFP)) )
    { // Next Check SVSH/SVMH settings to see if settings are affected by PMM15
        if ((SVSMHCTL & SVSHE) && (!(SVSMHCTL & SVSHFP)))
        {
            if ( (!(SVSMHCTL & SVSHMD)) ||
                ((SVSMHCTL & SVSHMD) && (SVSMHCTL & SVSMHACE)) )
                return 1; // SVSH affected configurations
        }
        if ((SVSMHCTL & SVMHE) && (!(SVSMHCTL & SVMHFP)) && (SVSMHCTL & SVSMHACE))
            return 1; // SVMH affected configurations
    }
    return 0; // SVS/M settings not affected by PMM15
}
```

PORT15**Digital I/O Module, Port 1 and 2****Function**

In-system debugging causes the PMALOCKED bit to be always set

Description

The port mapping controller registers cannot be modified when single-stepping or halting at break points between a valid password write to the PMAPWD register and the expected lock of the port mapping (PMAP) registers. This causes the PMAPLOCKED bit to remain set and not clear as expected.

NOTE: This erratum only applies to in-system debugging and is not applicable when operating in free-running mode.

Workaround

Do not single step through or place break points in the port mapping configuration section of code.

RF1A1**RF1A Module****Function**

The PLL lock detector output is not 100% reliable

Description

The PLL lock detector output is not 100% reliable and might toggle even if the PLL is in lock. The PLL is in lock if the lock detector output has a positive transition or is constantly logic high. The PLL is not in lock if the lock detector output is constantly logic low. It is not recommended to check for PLL lock by reading PKTSTATUS[0] with GDOx_CFG = 0x0A or PKTSTATUS[2] register with GDOx_CFG = 0x0A (x = 0 or 2).

Workaround

PLL lock can be checked reliably by these methods:

- Program register IOCFGx.GDOx_CFG = 0x0A and use the lock detector output available on the GDOx pin as an interrupt for the MCU. A positive transition on the GDOx pin means that the PLL is in lock. It is important to disable for interrupt when waking the chip from SLEEP state as the wake-up might cause the GDOx pin to toggle when it is programmed to output the lock detector.
- or
- Read register FSCAL1. The PLL is in lock if the register content is different from 0x3F.

With both of the above workarounds the CC1101 PLL calibration should be carried out with the correct settings for TEST0.VCO_SEL_CAL_EN and FSCAL2.VCO_CORE_H_EN. These settings are depending on the operating frequency and are calculated automatically by SmartRF® Studio.

Note that the TEST0 register content is not retained in SLEEP state, and thus it is necessary to write to this register as described here when returning from the SLEEP state.

RF1A2
RF1A Module
Function

RXFIFO overflow flag does not work as intended

Description

In addition to having a 64-byte long RX FIFO, the CC430 has a one byte long pre-fetch buffer between the FIFO and the RF1A module. It also has buffers for status registers and CRC bytes. If more than 65 bytes have been received (the FIFO and the pre-fetch buffer are full) without reading the RX FIFO, the radio will enter RXFIFO_OVERFLOW state. There are, however, some cases where the radio will be stuck in RX state instead of entering RXFIFO_OVERFLOW state. Below is a table showing the register settings that will cause this problem. APPEND_STATUS is found in the PKTCTRL1 register, and CRC_EN is found in the PKTCTRL0 register.

Setting IOCFGx=0x06 should mean that the GDO signal is deasserted when the RXFIFO overflows. In the cases where the radio is stuck in RX state, the GDOx pin will not be deasserted.

When the radio is stuck in this RX state it draws current as if it was in the RX state, but it will not be able to receive any more data. The only way to get out of this state is to issue an SIDLE strobe and then flush the FIFO (SFRX).

Workaround

In applications where the packets are short enough to fit in the RX FIFO and one wants to wait for the whole packet to be received before starting to read the RX FIFO, for variable packet length mode (PKTCTRL0.LENGTH_CONFIG=1) the PKTLEN register should be set to 61 to make sure the whole packet including status bytes are 64 bytes or less (length byte (61) + 61 payload bytes + 2 status bytes = 64 bytes) or PKTLEN = 62 if fixed packet length mode is used (PKTCTRL0.LENGTH_CONFIG=0). In application where the packets do not fit in the RX FIFO, one must start reading the RX FIFO before it reaches its limit (64 bytes).

RF1A3
RF1A Module
Function

Extra Byte Transmitted in TX

Description

If transmission is aborted (exits TX mode) during the transmission of the first half of any byte, there is a repetition of the first byte in the next transmission. This issue is caused by a state machine controlling the mod_rd_data signal in the modulator. This signal asserts at the start of transmission of each full byte, then deasserts after half the byte has been transmitted. If the transmission is aborted after a byte has started but before half the byte is transmitted, this signal remains asserted and the first byte in the next transmission is repeated.

Workaround

As long as the packet handling features of the CC430 are used, this is not a problem because the chip always exits TX mode after the transmission of the last bit in the last byte of the packet. If, however, the packet handling features are disabled (MDMCFG2.SYNC_MODE=0) and TX mode is manually exited by strobing IDLE, ensure that the IDLE strobe is being issued after clocking out 12 dummy bits (8 dummy bits are necessary due to the TX latency, but because this would mean that transmission is aborted within the first half of a byte, 4 extra bits are added).

RF1A5	<i>RF1A Module</i>
Function	FIFO Radio Core Interrupt may be triggered independent of the RFINx condition being met
Description	<p>The radio core interrupt flags (RFIFGx) may be set and could generate a radio core interrupt although the corresponding radio input (RFINx) signal condition has not been met.</p> <p>This is true for the FIFO Mapped Control Signals RFIFG3, RFIFG4, RFIFG5, RFIFG6, RFIFG7, RFIFG8, RFIFG9 (negative edge), and RFIFG10 (negative edge).</p>
Workaround	When handling the radio core interrupts RFIFG3 to RFIFG10, proceed with the ISR only after verifying that the RFINx signal respective to the RFIFGx flag is active.
RF1A6	<i>RF1A Module</i>
Function	LVERR flag set when radio in SLEEP or IDLE and VCORE = 0 or 1
Description	The low-voltage error flag (LVERR) is set when the radio is in the SLEEP or IDLE state and VCORE = 0 or 1, which is contrary to the behavior specified in the <i>CC430 User's Guide</i> .
Workaround	None
RF1A8	<i>RF1A Module</i>
Function	RF1AIN10 bit does not reset after the first byte of the RX FIFO is read
Description	The intended behavior of the RF1AIN10 bit is that it is set when the last byte is received (into the RX FIFO) and reset when the first byte is read from the RX FIFO. However, the RF1AIN10 bit does not reset after the first byte of the RX FIFO is read.
Workaround	Use RF1AIN9 for RX handling instead. To verify the RX packet CRC, enable the RF1A option to append the CRC_OK bit to the end of the RX packet. The CRC_OK bit can be checked after reading out the RX FIFO buffer.
RTC4	<i>RTC Module</i>
Function	RTC clock calibration maybe offset by +2 ppm
Description	When using the RTC clock calibration feature, the RTCCLK frequency maybe offset by +2 ppm after the calibration procedure is completed. This affects both up and down calibration.
Workaround	None
SYS16	<i>System Module</i>
Function	Fast V _{CC} ramp after device power up may cause a reset
Description	At initial power-up, after V _{CC} crosses the bownout threshold and reaches a constant level, an abrupt ramp of V _{CC} at a rate dV/dT > 1V/100μs can cause a brownout condition to be incorrectly detected even though V _{CC} does not fall below the brownout threshold. This causes the device to undergo a reset.
Workaround	Use a controlled V _{CC} ramp to power the device.

TAB23	<i>Timer_A/Timer_B Module</i>
Function	TAxR read can be corrupted when TAxR = TAxCCR0
Description	When a timer in Up mode is stopped and the counter register (TAxR) is equal to the TAxCCR0 value, a read of the TAR register may return an unexpected result.
Workaround	<ul style="list-style-type: none"> • Use Up/Down mode instead of Up mode. or • In Up mode, use the timer interrupt instead of halting the counter and reading out the value in TAxR. or • When halting the timer counter in 'Up' mode, reinitialize the timer before starting to run again.
UCS6	<i>Universal Clock System Module</i>
Function	USCI source clock does not turn off in LPM3/4 when UART is idle
Description	The USCI clock source (ACLK/SMCLK) remains enabled in LPM3 and LPM4 when the USCI is configured in UART mode and the communication is idle (UCSWRST = 0 but no TX or RX currently executing). This is contrary to the expected automatic clock activation described in the user's guide and can lead to higher current consumption in low-power modes, depending on the oscillator that feeds ACLK/SMCLK.
Workaround	Use the oscillator that is already active in LPM3 (ACLK) to source the USCI and use the low-power baud rate generator (UCOS16 = 0). For UART baud rates where a fast SMCLK sourced by the internal DCO is required, use LPM0 instead of LPM3.
UCS7	<i>Universal Clock System Module</i>
Function	DCO drifts when servicing short ISRs when in LPM0 or exiting active from ISRs for short periods of time
Description	<p>The FLL uses two rising edges of the reference clock to compare against the DCO frequency and decide on the required modifications to the DCOx and MODx bits. If the device is in a low-power mode with FLL disabled (LPM0 with DCO not sourcing ACLK/SMCLK or LPM2, LPM3, LPM4 where SCG1 bit is set) and enters a state that enables FLL (enter ISR from LPM0/LPM2 or exit active from ISRs) for a period less than three reference clock cycles, then the FLL will cause the DCO to drift.</p> <p>This occurs because the FLL immediately begins comparing an active DCO with its reference clock and making the respective modifications to the DCOx and MODx bits. If the FLL is not given sufficient time to capture a full reference clock cycle (two reference clock periods) and adjust accordingly (one reference clock period), then the DCO keeps drifting each time the FLL is enabled.</p>
Workaround	<ul style="list-style-type: none"> • If DCO is not sourcing ACLK or SMCLK in the application, use LPM1 instead of LPM0 to make sure FLL is disabled when interrupt service routine is serviced. or • When exiting active from ISRs, insert a delay of at least three reference clock periods. To save on power budget, the three reference clock periods could also be spent in LPM0 with TimerA or TimerB using ACLK/SMCLK sourced from DCO. This way, the FLL and DCO are still active in LPM0.

UCS9**Universal Clock System Module****Function**

Digital Bypass mode prevents entry into LPM4

Description

When entering LPM4, if an external digital input applied to XT1 in HF mode or XT2 is not turned off, the PMM does not switch to low-current mode causing higher than expected power consumption.

Workaround

Before entering LPM4:

- Switch to a clock source other than external bypass digital input
or
- Turn off external bypass mode (UCSCTL6.XT1BYPASS = 0)

UCS10**Universal Clock System Module****Function**

Modulation causes shift in DCO frequency

Description

When the FLL is enabled, the DCO frequency can be tracked automatically by modifying the DCOx and MODx bits. The MODx bits switch between the frequency selected by the DCO bits and the next higher frequency set by (DCO + 1). The erroneous behavior is seen when the FLL is tracking close to a DCO step boundary and the MOD counter is expected to rollover but, instead, the DCO bits increment and the MOD bits decrement. This causes the DCO to shift by up to 12% and remain at an increased frequency until approximately 15 REFCLK cycles have elapsed. The frequency reverts to the expected value immediately afterward.

For example, the modulator moves from DCOx = n and MODx = 31 to DCOx = n + 1 and MODx = 30, causing a large increase in the DCO frequency.

Applications could be impacted as follows:

- When using the DCO frequency for asynchronous serial communication and timer operation, the effect can be seen as corrupted data or incorrect timing events.

Workaround

- Change the clock source from the DCO to an external crystal oscillator (for example, XT1 or XT2, if available on the device) during the critical timing phase.
or
- Implement a software FLL, comparing the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture and tuning the value of the DCO and MOD bits periodically.
or
- Execute the following sequence in periodic intervals.
 1. Disable peripherals sourced by the DCO such as UART and timer.
 2. Turn on the FLL.
 3. Wait the worst case settling time of $32 \times 32 \times f_{\text{FLLREFCLK}}$ to allow the FLL to lock to the target frequency.
 4. Turn off the FLL.
 5. Compare the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture.
 - If the DCO frequency is higher than expected, repeat from step (2) until the frequency reaches the expected range.
 - Else proceed with code execution.

See the application report *UCS10 Guidance* ([SLAA489](#)) for information regarding working with this erratum. This erratum does not affect proper operation of the CPU when MCLK = DCO/FLL and is set to the maximum clock frequency specified in the

device-specific data sheet.

USCI26

USCI Module

Function

t_{buf} parameter violation in I²C multi-master mode

Description

In multi-master I²C systems, the timing parameter t_{buf} (bus free time between a stop condition and the following start) is not ensured to match the I²C specification of 4.7 μ s in standard mode and 1.3 μ s in fast mode. If the UCTXSTT bit is set during a running I²C transaction, the USCI module waits and issues the start condition on bus release, causing the violation to occur.

NOTE: It is recommended to check if UCBBUSY bit is cleared before setting UCTXSTT = 1.

Workaround

None

USCI30**USCI Module****Function**

I2C mode master receiver / slave receiver

Description

The USCI I2C module, when configured as a receiver (master or slave), performs a double-buffered receive operation. For example, in a transaction of two bytes, after the first byte is moved from the receive shift register to the receive buffer, the byte is acknowledged and the state machine allows the reception of the next byte.

If the receive buffer has not been cleared of its contents by reading the UCBxRXBUF register by the time the seventh bit of the following data byte is received, an error condition may occur on the I2C bus. Depending on the USCI configuration, the following may occur:

- If the USCI is configured as an I2C master receiver, an unintentional repeated start condition can be triggered or the master can switch into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case.
- If the USCI is configured as I2C slave receiver, the slave can switch to an idle state, stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine notifies the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the seventh bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition does not occur.

Workaround

The error condition can be avoided by servicing the UCBxRXIFG in a timely manner. This can be done by (a) servicing the interrupt and ensuring UCBxRXBUF is read promptly or (b) using the DMA to automatically read bytes from receive buffer upon UCBxRXIFG being set.

OR

If the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLOW is set for at least three USCI bit clock cycles; that is, $3 \times t_{\text{BitClock}}$.

NOTE: The last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes, follow the workaround.

Code flow for workaround:

1. Enter RX ISR for reading receiving bytes
2. Check if UCSCLOW.UCBxSTAT == 1
3. If no, repeat step 2 until set.
4. If yes, repeat step 2 for a time period $> 3 \times t_{\text{BitClock}}$, where $t_{\text{BitClock}} = 1/f_{\text{BitClock}}$
5. If window of $3 \times t_{\text{BitClock}}$ cycles has elapsed, it is safe to read UCBxRXBUF.

WDG4
Watchdog Module
Function

The WDT failsafe can be disabled

Description

The UCS is capable of masking clock requests (ACLK, SMCLK, MCLK) from peripheral modules; see request enable (REQEN) bits in the UCS control register, UCSCTL8.

The clock request logic of the UCS is used by the WDT module to ensure a fail-safe clock source in all low-power modes. Therefore, de-asserting the request enable bit of the watchdog clock source (xCLKREQEN = 0) allows the respective clock to be disabled upon entry into a low-power mode. Without an active clock source, the WDT timer stops incrementing and a watchdog event does not occur.

Workaround

None

Appendix A Prior Revisions

None

Revision History

Changes from H Revision (June 2011) to I Revision**Page**

- Changed PMM11 description 19

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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